



REFLOW OVEN RK 360

Infrared + Air circulation + Air cooling,
Pb-free Reflow Oven

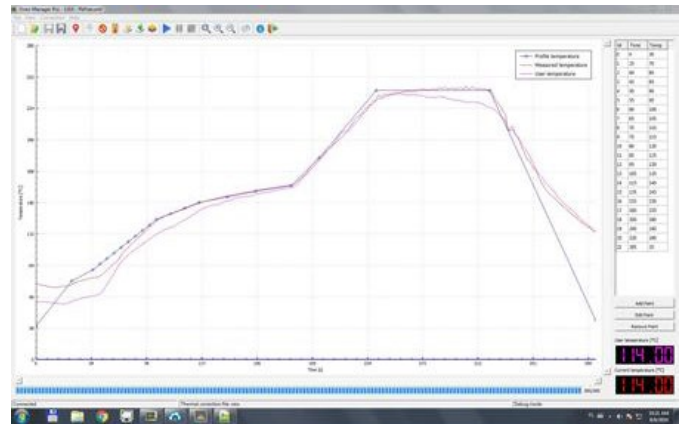
Surface mounting of units on boards require the exposure of the device package to high temperature to melt the lead finish for board soldering. A lot of the alternative "lead-free" solder materials being considered for use in IC assembly today require a peak soldering temperature of about 250 to 260 deg C,

versus the peak temperature of 230 to 235 deg C for Sn-Pb solder. This means that lead-free ICs require a higher temperature during board assembly and are therefore exposed to greater thermomechanical stress during the process.

This oven offers a complete system for today's solder/lead-free soldering requirements (260°C). The computer control allows for a freely programmable temperature curve. A high-performance heating element with forced-air heating ensures a uniform soldering zone across the entire soldering area. This cost-effective system offers high production output (4–5 minutes per cycle for 300 x 220 mm boards) and is ideal for small to medium-sized SMD production. The static soldering process provides high stability and stability, particularly important for fine-pitch SMD soldering.

Features

- Infrared Array + Force Air (high volume, low pressure) heating method.
- Heating system for top and bottom - separately and selectively controlled
- Free programmable control for temperature curve setting.
- Dual channel air circulation - internal cooling fans for fast cool down performance
- Fully Automatic, fully static (non moving rail) operation, single or double-sided board soldering.
- Large transparent glass window see through the soldering process with high temperature
- Internal complete high gloss stainless steel construction, high IR efficiency and easy to clean, maintenance.
- Top Open design for quick access to heating element and service.
- PC software for graphical interface mode–Ethernet and USB Interface for external PC



Specification

- Maximum heating area: 460 x 410mm
- Free programable in graphical mode
- 6 thermocouples inside heating chamber
- 1 interface for additional thermocouple – direct measurement on the PCB
- Fume extractor interface – diameter 80mm
- Maximum Temperature: 290 °C
- Operation environment: 0-40 °C
- Maximum power consumption: 3500 W / 1000 W Typ.
- Power supply: AC230V / 50-60Hz
- Weight: 55kg
- Dimension: 675 x 630 x 300 mm